

Biancun Xie

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/11177857/publications.pdf>

Version: 2024-02-01

6
papers

65
citations

2682572

2
h-index

2550090

3
g-index

6
all docs

6
docs citations

6
times ranked

57
citing authors

#	ARTICLE	IF	CITATIONS
1	Coupling analysis of through-silicon via (TSV) arrays in silicon interposers for 3D systems. , 2011, , .		23
2	Electrical-thermal modeling of through-silicon via (TSV) arrays in interposer. International Journal of Numerical Modelling: Electronic Networks, Devices and Fields, 2013, 26, 545-559.	1.9	13
3	Electromagnetic modeling of non-uniform through-silicon via (TSV) interconnections. , 2012, , .		11
4	FDFD Modeling of Signal Paths With TSVs in Silicon Interposer. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 708-717.	2.5	10
5	Modeling and analysis of SSN in silicon and glass interposers for 3D systems. , 2012, , .		7
6	FDFD Nonconformal Domain Decomposition Method for the Electromagnetic Modeling of Interconnections in Silicon Interposer. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 496-504.	2.2	1